

February 2001 Revised May 2005

74LCX162373

Low Voltage 16-Bit Transparent Latch with 5V Tolerant Inputs and Outputs and 26 Ω Series Resistor

General Description

The LCX162373 contains sixteen non-inverting latches with 3-STATE outputs and is intended for bus oriented applications. The device is byte controlled. The flip-flops appear transparent to the data when the Latch Enable (LE) is HIGH. When LE is LOW, the data that meets the setup time is latched. Data appears on the bus when the Output Enable $(\overline{\text{OE}})$ is LOW. When $\overline{\text{OE}}$ is HIGH, the outputs are in a high impedance state.

The LCX162373 is designed for low voltage (2.5V or 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment. The 26Ω series resistor in the output helps reduce output overshoot and undershoot.

The LCX162373 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- 2.3V-3.6V V_{CC} specifications provided
- \blacksquare Equivalent 26 Ω series resistor outputs
- \blacksquare 6.2 ns t_{PD} max (V $_{CC}$ = 3.3V), 20 μA I_{CC} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- ± 12 mA output drive ($V_{CC} = 3.0V$)
- Implements proprietary noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V

Machine model > 200V

Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA) (Preliminary)

Note 1: To ensure the high-impedance state during power up or down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

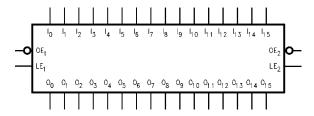
Ordering Code:

Order Number	Package Number	Package Description
74LCX162373GX (Note 2)	BGA54A (Preliminary)	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide [TAPE and REEL]
74LCX162373MEA (Note 3)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74LCX162373MTD (Note 3)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 2: BGA package available in Tape and Reel only.

Note 3: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol

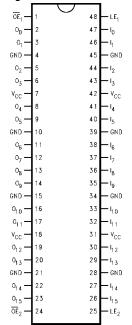


© 2005 Fairchild Semiconductor Corporation

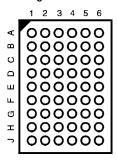
DS500443

Connection Diagrams

Pin Assignment for SSOP and TSSOP



Pin Assignment for FBGA



(Top Thru View)

Pin Descriptions

Pin Names	Description
OE _n	Output Enable Input (Active LOW)
LEn	Latch Enable Input
I ₀ –I ₁₅	Inputs
O ₀ -O ₁₅	Outputs
O ₀ -O ₁₅ NC	No Connect

FBGA Pin Assignments

	1	2	3	4	5	6
Α	O ₀	NC	OE ₁	LE ₁	NC	I ₀
В	O ₂	O ₁	NC	NC	I ₁	I ₂
С	O ₄	O ₃	V _{CC}	V _{CC}	l ₃	I ₄
D	O ₆	O ₅	GND	GND	l ₅	I ₆
E	Ο ₈	O ₇	GND	GND	I ₇	I ₈
F	O ₁₀	O ₉	GND	GND	l ₉	I ₁₀
G	O ₁₂	O ₁₁	V _{CC}	V _{CC}	I ₁₁	I ₁₂
Н	O ₁₄	O ₁₃	NC	NC	I ₁₃	I ₁₄
J	O ₁₅	NC	OE ₂	LE ₂	NC	I ₁₅

Truth Tables

Inputs			Outputs
LE ₁	OE ₁	I ₀ –I ₇	O ₀ -O ₇
Х	Н	Х	Z
Н	L	L	L
Н	L	Н	Н
L	L	Χ	O_0

	Inputs		Outputs
LE ₂	OE ₂	I ₈ -I ₁₅	O ₈ -O ₁₅
Х	Н	Х	Z
Н	L	L	L
Н	L	Н	Н
L	L	Х	O ₀

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial Z = High Impedance

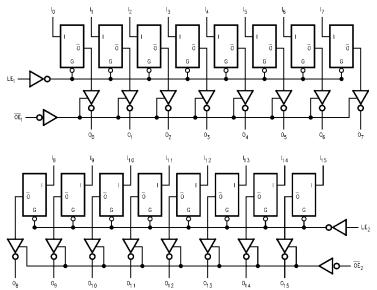
 O_0 = Previous O_0 before HIGH-to-LOW transition of Latch Enable

Functional Description

The LCX162373 contains sixteen D-type latches with 3-STATE standard outputs. The device is byte controlled with each byte functioning identically, but independent of the other. Control pins can be shorted together to obtain full 16-bit operation. The following description applies to each byte. When the Latch Enable (LE_n) input is HIGH, data on the I_n enters the latches. In this condition the latches are transparent, i.e. a latch output will change state each time

its I input changes. When LE_n is LOW, the latches store information that was present on the I inputs a setup time preceding the HIGH-to-LOW transition of LE_n . The 3-STATE standard outputs are controlled by the Output Enable (\overline{OE}_n) input. When \overline{OE}_n is LOW, the standard outputs are in the 2-state mode. When \overline{OE}_n is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the latches.

Logic Diagrams



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings(Note 4)

Symbol	Parameter	Value	Conditions	Units
V _{CC}	Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	-0.5 to +7.0		V
V _O	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		-0.5 to $V_{CC} + 0.5$	Output in HIGH or LOW State (Note 5)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current		V _O < GND	mA
		+50	V _O > V _{CC}	IIIA
Io	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current per Supply Pin	±100		mA
I _{GND}	DC Ground Current per Ground Pin	±100		mA
T _{STG}	Storage Temperature	-65 to +150		°C

Recommended Operating Conditions (Note 6)

Symbol	Parameter			Max	Units
V _{CC}	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	V
V _I	Input Voltage		0	5.5	V
Vo	Output Voltage	HIGH or LOW State	0	V _{CC}	V
		3-STATE	0	5.5	V
I _{OH} /I _{OL}	Output Current	$V_{CC} = 3.0V - 3.6V$		12	
		$V_{CC} = 2.7V - 3.0V$		±8	mA
		$V_{CC} = 2.3V - 2.7V$		±4	
T _A	Free-Air Operating Temperature		-40	85	°C
Δt/ΔV	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V		0	10	ns/V

Note 4: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 6: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V _{cc}	T _A = -40°C	C to +85°C	Units
Зупівої	Parameter	Conditions	(V)	Min	Max	Ullits
V _{IH}	HIGH Level Input Voltage		2.3 – 2.7	1.7		V
			2.7 - 3.6	2.0		v
V _{IL}	LOW Level Input Voltage		2.3 – 2.7		0.7	V
			2.7 - 3.6		0.8	V
V _{OH}	HIGH Level Output Voltage	I _{OH} = -100 μA	2.3 - 3.6	V _{CC} - 0.2		
		I _{OH} = -4 mA	2.3	1.8		
		$I_{OH} = -4 \text{ mA}$	2.7	2.2		V
		$I_{OH} = -6 \text{ mA}$	3.0	2.4		
		$I_{OH} = -8 \text{ mA}$	2.7	2.0		
		I _{OH} = -12 mA	3.0	2.0		
V _{OL}	LOW Level Output Voltage	I _{OL} = 100 μA	2.3 - 3.6		0.2	
		I _{OL} = 4 mA	2.3		0.6	
		I _{OL} = 4 mA	2.7		0.4	V
		I _{OL} = 6 mA	3.0		0.55	V
		I _{OL} = 8 mA	2.7		0.6	
		I _{OL} = 12 mA	3.0		0.8	
lı	Input Leakage Current	$0 \leq V_I \leq 5.5V$	2.3 - 3.6		±5.0	μА
l _{OZ}	3-STATE Output Leakage	$0 \le V_O \le 5.5V$	2.3 - 3.6		±5.0	۸
		$V_I = V_{IH}$ or V_{IL}				μА

Note 5: I_O Absolute Maximum Rating must be observed.

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC}	T _A = -40°	C to +85°C	Units
Syllibol	Parameter	Conditions	(V) Min Max		Oilles	
I _{OFF}	Power-Off Leakage Current	V_I or $V_O = 5.5V$	0		10	μА
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	2.3 – 3.6		20	цΑ
		$3.6V \le V_I, V_O \le 5.5V \text{ (Note 7)}$	2.3 – 3.6		±20	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} -0.6V	2.3 - 3.6		500	μΑ

Note 7: Outputs disabled or 3-STATE only.

AC Electrical Characteristics

	Parameter		$T_A = -40$ °C to $+85$ °C, $R_L = 500\Omega$					
Symbol		V _{CC} = 3.	$V_{CC}=3.3V\pm0.3V$		= 2.7V V _{CC} =		5V ± 0.2V	Units
Syllibol	Fai ameter	C _L =	50 pF	C _L =	50 pF	C _L = 30 pF		Ullits
		Min	Max	Min	Max	Min	Max	1
t _{PHL}	Propagation Delay	1.5	6.2	1.5	6.7	1.5	7.4	ns
t_{PLH}	I _n to O _n	1.5	6.2	1.5	6.7	1.5	7.4	115
t _{PHL}	Propagation Delay	1.5	6.3	1.5	7.2	1.5	7.6	ns
t_{PLH}	LE to O _n	1.5	6.3	1.5	7.2	1.5	7.6	115
t _{PZL}	Output Enable Time	1.5	6.9	1.5	7.3	1.5	9.0	ns
t_{PZH}		1.5	6.9	1.5	7.3	1.5	9.0	115
t _{PLZ}	Output Disable Time	1.5	6.0	1.5	6.3	1.5	7.2	ns
t_{PHZ}		1.5	6.0	1.5	6.3	1.5	7.2	115
t _S	Setup Time, I _n to LE	2.5		2.5		3.0		ns
t _H	Hold Time, I _n to LE	1.5		1.5		2.0		ns
t _W	LE Pulse Width	3.0		3.0		3.5		ns
toshl	Output to Output Skew (Note 8)		1.0					ns
toslh			1.0					113

Note 8: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}). Parameter guaranteed by design.

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C	Units
Cymbol	raidilleter	Conditions	(V)	Typical	J.III.S
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	0.35	V
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	0.25	V
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	-0.35	V
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	-0.25	٧

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	V _{CC} = Open, V _I = 0V or V _{CC}	7	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3V$, $V_{I} = 0V$ or V_{CC} , $f = 10$ MHz	20	pF

AC LOADING and WAVEFORMS Generic for LCX Family

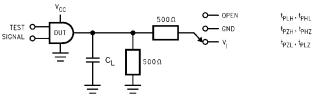
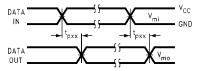
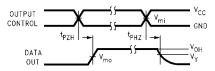


FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)

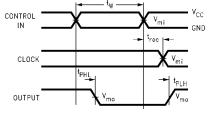
Test	Switch		
t _{PLH} , t _{PHL}	Open		
t _{PZL} , t _{PLZ}	6V at V_{CC} = 3.3 \pm 0.3V, and 2.7V V_{CC} x 2 at V_{CC} = 2.5 \pm 0.2V		
t _{PZH} , t _{PHZ}	GND		



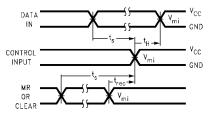
Waveform for Inverting and Non-Inverting Functions



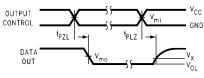
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and $t_{\rm rec}$ Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

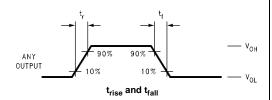
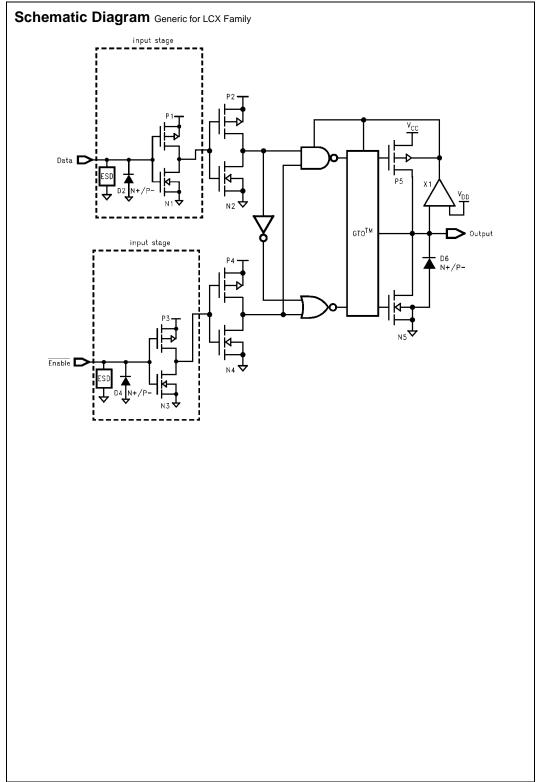
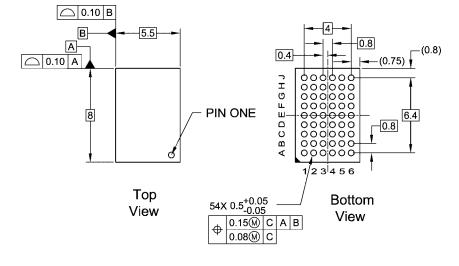


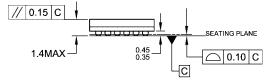
FIGURE 2. Waveforms (Input Characteristics; f =1MHz, $t_r = t_f = 3ns$)

Symbol	V _{CC}			
	3.3V ± 0.3V	2.7V	2.5V ± 0.2V	
V _{mi}	1.5V	1.5V	V _{CC} /2	
V _{mo}	1.5V	1.5V	V _{CC} /2	
V _x	V _{OL} + 0.3V	V _{OL} + 0.3V	V _{OL} + 0.15V	
V _y	V _{OH} – 0.3V	V _{OH} – 0.3V	V _{OH} – 0.15V	



Physical Dimensions inches (millimeters) unless otherwise noted



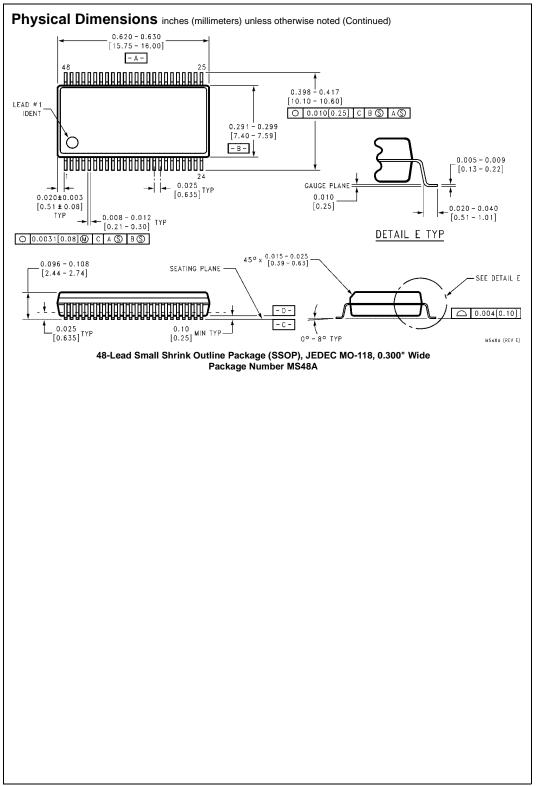


NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- **B. ALL DIMENSIONS IN MILLIMETERS**
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
 .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
 D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A Preliminary



Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-99. 9.20 8.10 50. O.2 C B A ALL LEAD TIPS PIN #1 IDENT LAND PATTERN RECOMMENDATION 0.1 C SEE DETAIL A 0.90+0.15 0.09-0.20 0.10±0.05 0.17-0.27 0.50 ♦ 0.13\@ A B\S C\S 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MC-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 1.00 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC 48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ON Semiconductor and III) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages.

Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

© Semiconductor Components Industries, LLC

www.onsemi.com